

2x100GBASE-SR4 QSPDD Optical Transceiver

Description

2x100GBASE-SR4 QSPDD transceiver is one kind of parallel transceiver, VCSEL and PIN array package is the key technique, through I2C system can contact with module. It is a Eight-Channel, Pluggable, Parallel, Fiber-Optic QSFP Double Density for 2x100 Gigabit Ethernet applications, high performance module for short-range multi-lane data communication and interconnect applications. It integrates eight data lanes in each direction with 8x25.78125Gbps bandwidth. Each lane can operate at 25.78125Gbps up to 70 m using OM3 fiber or 100 m using OM4 fiber. These modules are designed to operate over multimode fiber systems using a nominal wavelength of 850nm. The electrical interface uses a 76 contact edge type connector. The optical interface uses an 24 fiber MTP (MPO) connector. This module incorporates proven circuit and VCSEL technology to provide reliable long life, high performance, and consistent service.

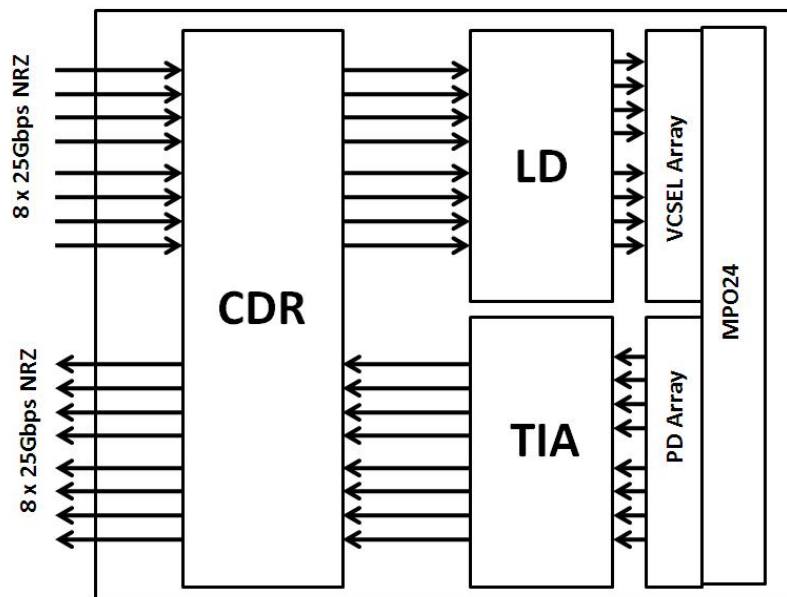


Figure 1. Module Block Diagram

Features

- 8 channels full-duplex transceiver modules
- Transmission data rate up to 26Gbps per channel
- 8 channels 850nm VCSEL array
- 8 channels PIN photo detector array
- Internal CDR circuits on both receiver and transmitter channels
- Support CDR bypass
- Low power consumption <4W
- Hot Pluggable QSFP DD form factor
- Maximum link length of 70m on OM3 Multimode Fiber (MMF)and 100m on OM4 MMF
- MPO24 connector receptacle
- Operating case temperature 0°C to +70°C
- 3.3V power supply voltage
- RoHS 6 compliant(lead free)

Applications

- ◆ IEEE 802.3bm 100GBASE SR4

Absolute Maximum Ratings

| Parameter | Symbol | Min | Max | Unit |
|----------------------------|--------|------|---------|------|
| Supply Voltage | Vcc | -0.3 | 3.6 | V |
| Input Voltage | Vin | -0.3 | Vcc+0.3 | V |
| Storage Temperature | Tst | -20 | 85 | °C |
| Case Operating Temperature | Top | 0 | 70 | °C |
| Humidity(non-condensing) | Rh | 5 | 95 | % |

Recommended Operating Conditions

| Parameter | Symbol | Min | Typical | Max | Unit |
|----------------------------|--------|------|----------|------|------|
| Supply Voltage | Vcc | 3.13 | 3.3 | 3.47 | V |
| Operating Case temperature | Tca | 0 | | 70 | °C |
| Data Rate Per Lane | fd | | 25.78125 | | Gbps |
| Humidity | Rh | 5 | | 85 | % |
| Power Dissipation | Pm | | | 4 | W |

Electrical Specifications

| Parameter | Symbol | Min | Typical | Max | Unit |
|--|------------------|----------------------|---------|-----------------|-------|
| Differential input impedance | Zin | 90 | 100 | 110 | ohm |
| Differential Output impedance | Zout | 90 | 100 | 110 | ohm |
| Differential input voltage amplitude aAmplitude | ΔV_{in} | 300 | | 1100 | mVp-p |
| Differential output voltage amplitude | ΔV_{out} | 500 | | 800 | mVp-p |
| Skew | Sw | | | 300 | ps |
| Bit Error Rate | BER | | | 5E-5 | |
| Input Logic Level High | V _{IH} | 2.0 | | V _{CC} | V |
| Input Logic Level Low | V _{IL} | 0 | | 0.8 | V |
| Output Logic Level High | V _{OH} | V _{CC} -0.5 | | V _{CC} | V |
| Output Logic Level Low | V _{OL} | 0 | | 0.4 | V |

Note:

- BER=5E-5; PRBS [2^31-1@25.78125Gbps](#). Pre-FEC
- Differential input voltage amplitude is measured between TxnP and TxnN.
- Differential output voltage amplitude is measured between RxnP and RxnN.

Optical Characteristics

Table 3 - Optical Characteristics

| Parameter | Symbol | Min | Typical | Max | Unit | Notes |
|---|------------------|---|---------|------|------|-----------------------|
| Transmitter | | | | | | |
| Centre Wavelength | λ_c | 840 | 850 | 860 | nm | - |
| RMS spectral width | $\Delta\lambda$ | - | - | 0.6 | nm | - |
| Average launch power, each lane | P _{out} | -8.4 | - | 2.4 | dBm | - |
| Optical Modulation Amplitude (OMA),each lane | OMA | -6.4 | | 3 | dBm | - |
| Transmitter and dispersion eye closure(TDEC),each lane | TDEC | | | 4.3 | dB | |
| Extinction Ratio | ER | 3 | - | - | dB | - |
| Average launch power of OFF transmitter, each lane | | | | -30 | dB | - |
| Eye Mask coordinates: X1, X2, X3, Y1, Y2, Y3 | | SPECIFICATION VALUES {0.3,0.38,0.45,0.35,0.41,0.5} | | | | Hit Ratio = 5x10-5 |
| Receiver | | | | | | |
| Centre Wavelength | λ_c | 840 | 850 | 860 | nm | - |
| Stressed receiver sensitivity in OMA | | | | -5.2 | dBm | 1 |
| Maximum Average power at receiver , each lane | | | | 2.4 | dBm | - |

| | | | | | | |
|---|--|-----|--|-------|-----|---|
| Minimum Average power at receiver , each lane | | | | -10.3 | dBm | |
| Receiver Reflectance | | | | -12 | dB | - |
| LOS Assert | | -30 | | | dBm | - |
| LOS De-Assert – OMA | | | | -7.5 | dBm | - |
| LOS Hysteresis | | 0.5 | | | dB | - |

Note:

1. Measured with conformance test signal at TP3 for BER = 5E-5 Per-FEC

Pin Description

| Pad | Logic | Symbol | Description | Plug Sequence ⁴ | Notes |
|--|-------|----------|-------------------------------------|----------------------------|-------|
| 39 | | GND | Ground | 1A | 1 |
| 40 | CML-I | Tx6n | Transmitter Inverted Data Input | 3A | |
| 41 | CML-I | Tx6p | Transmitter Non-Inverted Data Input | 3A | |
| 42 | | GND | Ground | 1A | 1 |
| 43 | CML-I | Tx8n | Transmitter Inverted Data Input | 3A | |
| 44 | CML-I | Tx8p | Transmitter Non-Inverted Data Input | 3A | |
| 45 | | GND | Ground | 1A | 1 |
| 46 | | Reserved | For future use | 3A | 3 |
| 47 | | VS1 | Module Vendor Specific 1 | 3A | 3 |
| 48 | | VccRx1 | 3.3V Power Supply | 2A | 2 |
| 49 | | VS2 | Module Vendor Specific 2 | 3A | 3 |
| 50 | | VS3 | Module Vendor Specific 3 | 3A | 3 |
| 51 | | GND | Ground | 1A | 1 |
| 52 | CML-O | Rx7p | Receiver Non-Inverted Data Output | 3A | |
| 53 | CML-O | Rx7n | Receiver Inverted Data Output | 3A | |
| 54 | | GND | Ground | 1A | 1 |
| 55 | CML-O | Rx5p | Receiver Non-Inverted Data Output | 3A | |
| 56 | CML-O | Rx5n | Receiver Inverted Data Output | 3A | |
| 57 | | GND | Ground | 1A | 1 |
| 58 | | GND | Ground | 1A | 1 |
| 59 | CML-O | Rx6n | Receiver Inverted Data Output | 3A | |
| 60 | CML-O | Rx6p | Receiver Non-Inverted Data Output | 3A | |
| 61 | | GND | Ground | 1A | 1 |
| 62 | CML-O | Rx8n | Receiver Inverted Data Output | 3A | |
| 63 | CML-O | Rx8p | Receiver Non-Inverted Data Output | 3A | |
| 64 | | GND | Ground | 1A | 1 |
| 65 | | NC | No Connect | 3A | 3 |
| 66 | | Reserved | For future use | 3A | 3 |
| 67 | | VccTx1 | 3.3V Power Supply | 2A | 2 |
| 68 | | Vcc2 | 3.3V Power Supply | 2A | 2 |
| 69 | | Reserved | For Future Use | 3A | 3 |
| 70 | | GND | Ground | 1A | 1 |
| 71 | CML-I | Tx7p | Transmitter Non-Inverted Data Input | 3A | |
| 72 | CML-I | Tx7n | Transmitter Inverted Data Input | 3A | |
| 73 | | GND | Ground | 1A | 1 |
| 74 | CML-I | Tx5p | Transmitter Non-Inverted Data Input | 3A | |
| 75 | CML-I | Tx5n | Transmitter Inverted Data Input | 3A | |
| 76 | | GND | Ground | 1A | 1 |
| <p>Note 1: QSFP-DD uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.</p> <p>Note 2: VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 4. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.</p> <p>Note 3: All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 kOhms and less than 100 pF.</p> <p>Note 4: Plug Sequence specifies the mating sequence of the host connector and module. The sequence is 1A, 2A, 3A, 1B, 2B, 3B. (see Figure 2 for pad locations) Contact sequence A will make, then break contact with additional QSFP-DD pads. Sequence 1A, 1B will then occur simultaneously, followed by 2A, 2B, followed by 3A, 3B.</p> | | | | | |

Table 1- Pad Function Definition

| Pad | Logic | Symbol | Description | Plug Sequence ⁴ | Notes |
|-----|-----------|----------|---|----------------------------|-------|
| 1 | | GND | Ground | 1B | 1 |
| 2 | CML-I | Tx2n | Transmitter Inverted Data Input | 3B | |
| 3 | CML-I | Tx2p | Transmitter Non-Inverted Data Input | 3B | |
| 4 | | GND | Ground | 1B | 1 |
| 5 | CML-I | Tx4n | Transmitter Inverted Data Input | 3B | |
| 6 | CML-I | Tx4p | Transmitter Non-Inverted Data Input | 3B | |
| 7 | | GND | Ground | 1B | 1 |
| 8 | LVTTL-I | ModSelL | Module Select | 3B | |
| 9 | LVTTL-I | ResetL | Module Reset | 3B | |
| 10 | | VccRx | +3.3V Power Supply Receiver | 2B | 2 |
| 11 | LVCOS-I/O | SCL | 2-wire serial interface clock | 3B | |
| 12 | LVCOS-I/O | SDA | 2-wire serial interface data | 3B | |
| 13 | | GND | Ground | 1B | 1 |
| 14 | CML-O | Rx3p | Receiver Non-Inverted Data Output | 3B | |
| 15 | CML-O | Rx3n | Receiver Inverted Data Output | 3B | |
| 16 | | GND | Ground | 1B | 1 |
| 17 | CML-O | Rx1p | Receiver Non-Inverted Data Output | 3B | |
| 18 | CML-O | Rx1n | Receiver Inverted Data Output | 3B | |
| 19 | | GND | Ground | 1B | 1 |
| 20 | | GND | Ground | 1B | 1 |
| 21 | CML-O | Rx2n | Receiver Inverted Data Output | 3B | |
| 22 | CML-O | Rx2p | Receiver Non-Inverted Data Output | 3B | |
| 23 | | GND | Ground | 1B | 1 |
| 24 | CML-O | Rx4n | Receiver Inverted Data Output | 3B | |
| 25 | CML-O | Rx4p | Receiver Non-Inverted Data Output | 3B | |
| 26 | | GND | Ground | 1B | 1 |
| 27 | LVTTL-O | ModPrsL | Module Present | 3B | |
| 28 | LVTTL-O | IntL | Interrupt | 3B | |
| 29 | | VccTx | +3.3V Power supply transmitter | 2B | 2 |
| 30 | | Vcc1 | +3.3V Power supply | 2B | 2 |
| 31 | LVTTL-I | InitMode | Initialization mode; In legacy QSFP applications, the InitMode pad is called LPMODE | 3B | |
| 32 | | GND | Ground | 1B | 1 |
| 33 | CML-I | Tx3p | Transmitter Non-Inverted Data Input | 3B | |
| 34 | CML-I | Tx3n | Transmitter Inverted Data Input | 3B | |
| 35 | | GND | Ground | 1B | 1 |
| 36 | CML-I | Tx1p | Transmitter Non-Inverted Data Input | 3B | |
| 37 | CML-I | Tx1n | Transmitter Inverted Data Input | 3B | |
| 38 | | GND | Ground | 1B | 1 |

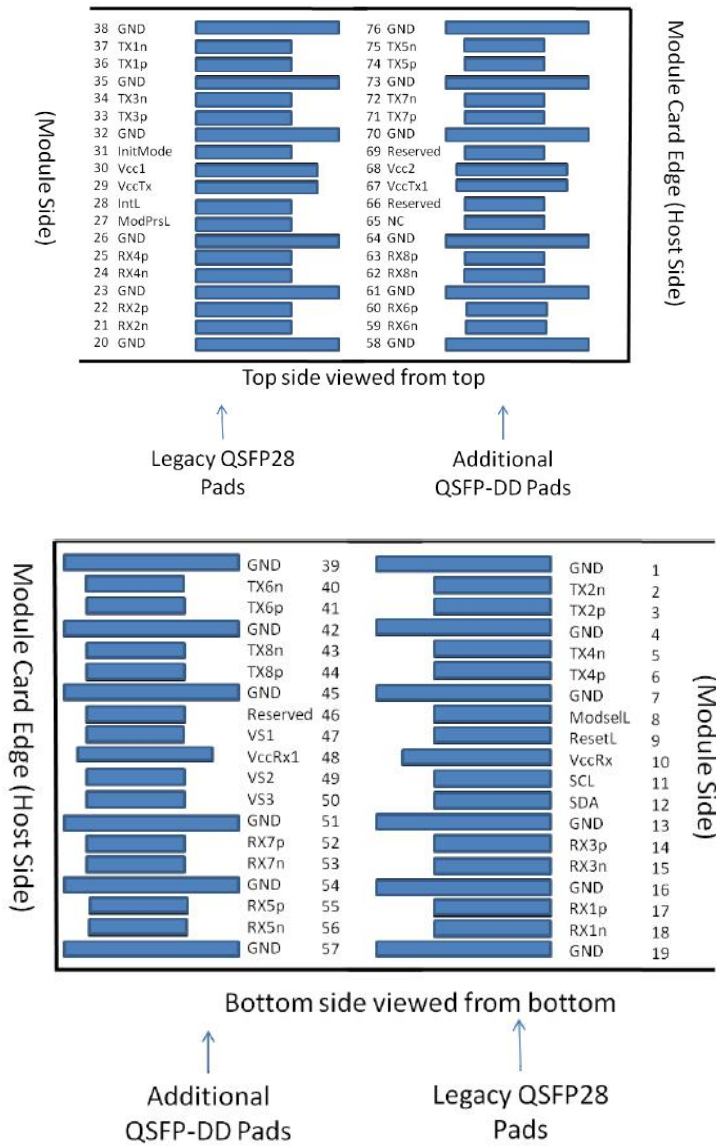


Figure 2. Electrical Pin-out Details

ModSel Pin

The ModSel is an input signal that must be pulled to Vcc in the QSFP-DD module. When held low by the host, the module responds to 2-wire serial communication commands. The ModSel allows the use of multiple QSFP-DD modules on a single 2-wire interface bus. When ModSel is “High”, the module shall not respond to or acknowledge any 2-wire interface communication from the host.

In order to avoid conflicts, the host system shall not attempt 2-wire interface communications within the ModSel de-assert time after any QSFP-DD modules are deselected. Similarly, the host must wait at least for the period of the ModSel assert time before communicating with the newly selected module. The assertion and de-asserting periods of different modules may overlap as long as the above timing requirements are met.

ResetL Pin

The ResetL signal shall be pulled to Vcc in the module. A low level on the ResetL signal for longer than the minimum pulse length (t_Reset_init) (See Table 13) initiates a complete module reset, returning all user module settings to their default state.

InitMode Pin

InitMode is an input signal. The InitMode signal must be pulled up to Vcc in the QSFP-DD module. The InitMode signal allows the host to define whether the QSFP-DD module will initialize under host software control (InitMode asserted High) or module hardware control (InitMode deasserted Low). Under host software control, the module shall remain in Low Power Mode until software enables the transition to High Power Mode, as defined in Section 7.5. Under hardware control (InitMode de-asserted Low), the module may immediately transition to High Power Mode after the management interface is initialized. The host shall not change the state of this signal while the module is present. In legacy QSFP applications, this signal is named LPMMode. See SFF-8679 for signal description.

ModPrsL Pin

ModPrsL must be pulled up to Vcc Host on the host board and grounded in module. The ModPrsL is asserted “Low” when module is inserted and deasserted “High” when module is physically absent from host connector.

IntL Pin

IntL is an output signal. The IntL signal is an open collector output and must be pulled to Vcc Host on the host board. When the IntL signal is asserted Low it indicates a change in module state, a possible module operational fault or a status critical to the host system. The host identifies the source of the interrupt using the 2-wire serial interface. The IntL signal is deasserted “High” after all set interrupt flags are read.

Power Supply Filtering

The host board should use the power supply filtering shown in Figure3.

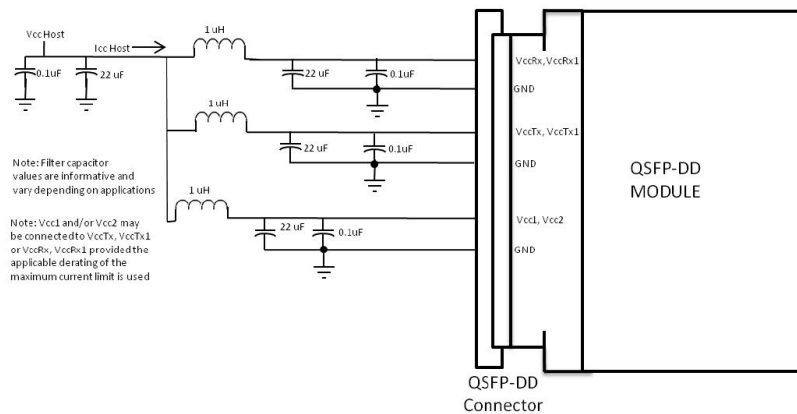


Figure 3. Host Board Power Supply Filtering

Optical Interface Lanes and Assignment

The optical interface port is a male MPO24 connector .

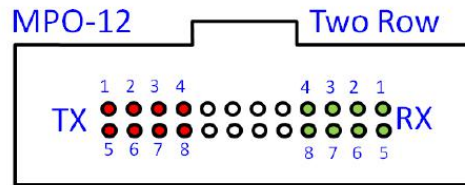


Figure 4. Optical Receptacle and Channel Orientation

DIAGNOSTIC MONITORING INTERFACE (OPTIONAL)

Digital diagnostics monitoring function is available on all QSFP DD products. A 2-wire serial interface provides user to contact with module. The structure of the memory is shown in Figure 5. The memory space is arranged into a lower, single page, address space of 128 bytes and multiple upper address space pages. This structure permits timely access to addresses in the lower page, e.g. Interrupt Flags and Monitors. Less time critical entries, e.g. serial ID information and threshold settings, are available with the Page Select function. The structure also provides address expansion by adding additional upper pages as needed. The interface address used is A0xh and is mainly used for time critical data like interrupt handling in order to enable a one-time-read for all data related to an interrupt situation. After an interrupt, IntL, has been asserted, the host can read out the flag field to determine affected channel and type of flag.

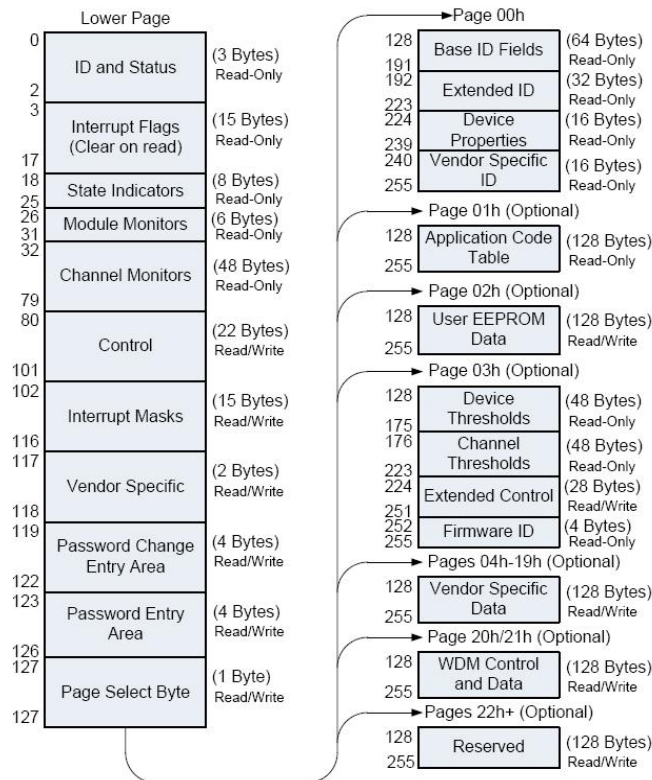


Figure 5. QSFP DD Memory Map

Table 16- Lower Page Overview (Lower Page)

| Address | Description | Type |
|-----------|---------------------------------|------------|
| 0 - 2 | Id and Status (3 bytes) | Read-only |
| 3 - 17 | Interrupt Flags (15 bytes) | Read-only |
| 18 - 25 | State Indicators (8 bytes) | Read-only |
| 26 - 31 | Module card Monitors (6 bytes) | Read-only |
| 32 - 79 | Channel Monitors (48 bytes) | Read-only |
| 80 - 101 | Control Fields (22 bytes) | Read/Write |
| 102 - 116 | Interrupt Flag Masks (15 bytes) | Read/Write |
| 117 - 118 | Reserved | Read/Write |
| 119 - 122 | Password Change Area (4 bytes) | Write-Only |
| 123 - 126 | Password Entry Area (4 bytes) | Write-Only |
| 127 | Page Select Byte | Read/Write |

Figure 6. Low Memory Map

Table 28- Upper Page 0 Overview (Page 00h)

| Address | Size (bytes) | Name | Description |
|------------------------|--------------|---------------------------------|--|
| Base ID Fields: | | | |
| 128 | 1 | Identifier | Identifier Type of module |
| 129 | 1 | Ext. Identifier | Extended Identifier |
| 130 | 1 | Connector Type | Code for media connector type |
| 131-138 | 8 | Specification compliance | Code for electronic compatibility or optical compatibility |
| 139 | 1 | Encoding | Code for serial encoding algorithm |
| 140 | 1 | BR, nominal | Nominal bit rate, units of 100 Mbits/s |
| 141 | 1 | Extended rate select compliance | Tags for extended rate select compliance |
| 142-146 | 5 | Link length | Link length / transmission media |
| 147 | 1 | Device technology | Device technology |
| 148-163 | 16 | Vendor name | Vendor name (ASCII) |
| 164 | 1 | Extended Module | Extended Module codes for InfiniBand |
| 165-167 | 3 | Vendor OUI | Vendor IEEE company ID |
| 168-183 | 16 | Vendor PN | Part number provided by vendor (ASCII) |
| 184-185 | 2 | Vendor rev | Revision level for part number provided by vendor (ASCII) |
| 186-187 | 2 | Wavelength or Copper | Nominal laser wavelength |

Figure7. Page 00 Memory Map

| | | | |
|-----------------------------------|----|----------------------------|---|
| | | cable Attenuation | (wavelength=value/20 in nm) or copper cable attenuation in dB at 2.5GHz (Adrs 186) and 5.0GHz (Adrs 187) |
| 188-189 | 2 | Wavelength tolerance | Guaranteed range of laser wavelength(+/-value) from nominal wavelength.(wavelength Tolerance=value/200 in nm) |
| 190 | 1 | Max case temp. | Maximum case temperature in degrees C |
| 191 | 1 | CC_BASE | Check code for base ID fields (addresses 128-190 inclusive) |
| Extended ID Fields: | | | |
| 192-195 | 4 | Options | Indicates which optional capabilities are implemented in the module |
| 196-211 | 16 | Vendor S/N | Vendor product serial number |
| 212-219 | 8 | Date Code | Vendor's manufacturing date code |
| 220 | 1 | Diagnostic Monitoring Type | Indicates which types of diagnostic monitoring are implemented in the module |
| 221-222 | 2 | Enhanced Options | Indicates which optional enhanced features are implemented in the module. |
| 223 | 1 | CC_EXT | Check code for the Extended ID Fields (addresses 192-222 inclusive) |
| 224-238 | 15 | Device Properties | Provides detailed information about the device |
| 239 | 1 | CC-PROP | Check code for the Device Properties Fields (addresses 224-2382 inclusive) |
| Vendor Specific ID Fields: | | | |
| 240-255 | 16 | Vendor-Specific | Vendor-specific ID information |

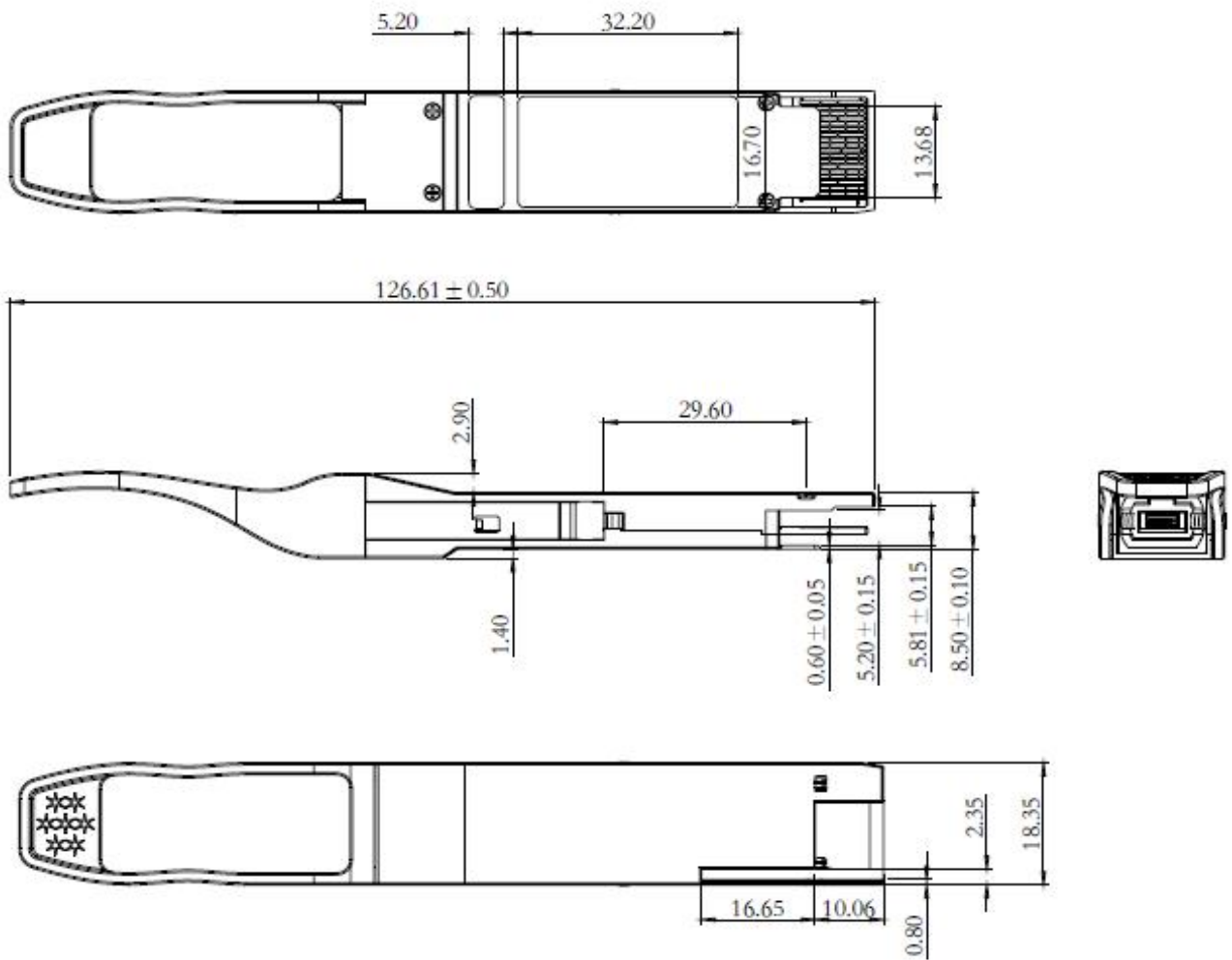
Timing for Soft Control and Status Functions

Table 13- Timing for QSFP-DD soft control and status functions

| Parameter | Symbol | Min | Max | Unit | Conditions |
|--|-----------------------|-----|------|------|---|
| MgmtInitDuration | Max MgmtInit Duration | | 2000 | ms | Time from power on ² , hot plug or rising edge of reset until completion of the MgmtInit State |
| ResetL Assert Time | t_reset_init | 2 | | us | Minimum pulse time on the ResetL signal to initiate a module reset. |
| IntL Assert Time | ton_IntL | | 200 | ms | Time from occurrence of condition triggering IntL until Vout:IntL=Vol |
| IntL Deassert Time | toff_IntL | | 500 | us | Time from clear on read ³ operation of associated flag until Vout:IntL=Voh. This includes deassert times for Rx LOS, Tx Fault and other flag bits. |
| Rx LOS Assert Time | ton_los | | 100 | ms | Time from Rx LOS state to Rx LOS bit set (value = 1b) and IntL asserted. |
| Rx LOS Assert Time (optional fast mode) | ton_losf | | 1 | ms | Time from Rx LOS state to Rx LOS bit set (value = 1b) and IntL asserted. |
| Rx LOS Deassert Time (optional fast mode) | toff_losf | | 3 | ms | Time from signal present to negation of Rx LOS status bit. |
| Tx Fault Assert Time | ton_Txfault | | 200 | ms | Time from Tx Fault state to Tx Fault bit set (value=1b) and IntL asserted. |
| Flag Assert Time | ton_flag | | 200 | ms | Time from occurrence of condition triggering flag to associated flag bit set (value=1b) and IntL asserted. |
| Mask Assert Time | ton_mask | | 100 | ms | Time from mask bit set (value=1b) ¹ until associated IntL assertion is inhibited |
| Mask Deassert Time | toff_mask | | 100 | ms | Time from mask bit cleared (value=0b) ¹ until associated IntL operation resumes |
| Application or Rate Select Change Time | t_ratesel | | 100 | ms | Time from change of state of Application or Rate Select bit ¹ until transmitter or receiver bandwidth is in conformance with appropriate specification |
| Note 1. Measured from the rising edge of SDA in the stop bit of the write transaction | | | | | |
| Note 2. Power on is defined as the instant when supply voltages reach and remain at or above the minimum level specified in Table 6. | | | | | |
| Note 3. Measured from the rising edge of SDA in the stop bit of the read transaction | | | | | |

Figure 9. Timing Specifications

Outline Drawing (mm)



.Unit:mm
.Unless Otherwise Specified, Tolerance ±0.1mm



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Specifications & design are subject to change without prior notice.

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